



ADVISORY/Applied Materials Hosts Interconnect Forum on "Improving Yield and Reliability for 65nm and Beyond"

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SANTA CLARA, Calif.--(BUSINESS WIRE)--Oct. 14, 2004--Applied Materials, Inc. (Nasdaq:AMAT)

What: Applied Materials Inc., the leader in interconnect process technology and services to the global semiconductor industry, is hosting a technical forum in conjunction with the Advanced Metallization Conference (AMC).

The forum will bring together key industry experts from IBM and Stanford University to discuss critical yield and reliability challenges that must be addressed to extend Moore's Law to 65nm and beyond. These include debonding, microfractures, electromigration, stress migration and packaging challenges, as well as the need for new planarization techniques such as Ecmp (electro-chemical mechanical planarization) to enable advanced low k integration.

When: Sunday, Oct. 17th, from 4:30pm to 6:00pm PST, reception to follow

Where: Del Mar Room, the Bahia Resort Hotel
998 West Mission Bay Drive, San Diego

Panel: Sandra Malhotra, Ph.D., Advanced BEOL Metals Integration, IBM Corporation
Andrew Simon, Ph.D., Advanced BEOL Metals Integration, IBM Corporation
Reinhold Dauskardt, Ph.D., Department of Materials Science and Engineering, Stanford University

Details: "We value the opportunity to meet with customers and to share leading-edge research at these technical forums," said Farhad Moghadam, senior vice president and general manager of Applied Materials' Thin Films Product Business Group. "By fostering greater insight and understanding of key issues, we can more effectively help drive manufacturing breakthroughs that give our customers the greatest competitive advantage."

During the technical sessions at this year's AMC, Applied Materials will present multiple papers showcasing breakthrough interconnect solutions. A few of the topics covered will include direct plating of copper on ruthenium, ALD (atomic layer deposition), hermetic sealing of low k pores, and development of an electroless cobalt capping process.

For the complete program and to register, visit:
http://www.appliedmaterials.com/about/amat_interconnect_forum.html

Applied Materials, Inc. (Nasdaq:AMAT) is the largest supplier of

products and services to the global semiconductor industry. Applied Materials' web site is www.appliedmaterials.com.

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